

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die		Silicon (Si)	7440-21-3	0.24195	100.0	12.925
			Subtotal	0.24195	100	12.925
Lead Frame		Phosphorous (P)	7723-14-0	0.0189	0.03	1.00983
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.68053	1.08	36.35388
		Copper (Cu)	7440-50-8	62.31248	98.89	3,328.73629
			Subtotal	63.01191	100	NaN
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.67424	7.7	142.8581
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	4.16765	12.0	222.636
	Filler	Silica fused	60676-86-0	27.78432	80.0	1,484.24
	Carbon Black	Carbon black	1333-86-4	0.10419	0.3	5.5659
			Subtotal	34.7304	100	NaN
Post-plating	Pure metal	Tin (Sn)	7440-31-5	1.79146	100.0	95.7
			Subtotal	1.79146	100	95.7
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.07489	100.0	4.00047
			Subtotal	0.07489	100	4.00047
Solder Wire	Pure metal	Tin (Sn)	7440-31-5	0.00747	5.0	0.399
	Pure metal	Silver (Ag)	7440-22-4	0.00224	1.5	0.1197
	Pure metal	Lead (Pb)	7439-92-1	0.13967	93.5	7.4613
			Subtotal	0.14938	100	7.98
			Total	99.99999	100	NaN

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